Materials Declaration

Package	LQFP
Body Size	20 X 20
LeadCount	184
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	5.53 E-02	40613
SiO2 Filler	86	5.95 E-01	436590
Phenol Resin	5	3.46 E-02	25383
Antimony_Sb2O3	0.4	2.77 E-03	2031
Brominated Resin	0.4	2.77 E-03	2031
Carbon Black	0.2	1.38 E-03	1015
	Sub-Total	**6.92 E-01**	**507662**

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	5.53 E-01	406026
Ni	3	1.73 E-02	12662
Si	0.65	3.74 E-03	2743
Mg	0.15	8.63 E-04	633
	Sub-Total	**5.75 E-01**	**422065**

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	3.50 E-03	2569

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	7.14 E-02	52372
	Sub-Total	**7.14 E-02**	**52372**

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	8.85 E-04	649

Chip

	% of Chip	Weight (g)	PPM
Si	100	7.04 E-04	517

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	5.02 E-03	3683
Ag Filler	74	1.43 E-02	10483
	Sub-Total	**1.93 E-02**	**14166**

Package Totals

Weight (g)	PPM
1.36 E+00	1000000

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

STS-ST-C

Note: The information provided in this declaration are true to the best of ADI's knowledge.

ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

7/7/05

Materials Declaration

Package	LQFP
Body Size	20 X 20
LeadCount	184
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	5.53 E-02	40613
SiO2 Filler	86	5.95 E-01	436590
Phenol Resin	5	3.46 E-02	25383
Antimony_Sb2O3	0.4	2.77 E-03	2031
Brominated Resin	0.4	2.77 E-03	2031
Carbon Black	0.2	1.38 E-03	1015
	Sub-Total	**6.92 E-01**	**507662**

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	5.53 E-01	406026
Ni	3	1.73 E-02	12662
Si	0.65	3.74 E-03	2743
Mg	0.15	8.63 E-04	633
	Sub-Total	**5.75 E-01**	**422065**

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	3.50 E-03	2569

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	6.06 E-02	44516
Pb	15	1.07 E-02	7856
	Sub-Total	**7.14 E-02**	**52372**

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	8.85 E-04	649

Chip

	% of Chip	Weight (g)	PPM
Si	100	7.04 E-04	517

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	5.02 E-03	3683
Ag Filler	74	1.43 E-02	10483
	Sub-Total	**1.93 E-02**	**14166**

Package Totals

Weight (g)	PPM
1.36 E+00	1000000

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

STS-ST-A

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